ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SSOP 20-28 LEAD					
Stress	**Sample Size**	**Device Hr./Cyc**	**Condition**	**Total Fails**	**Fail Percentage**
HAST	565	56,500	130°C, 85%RH	0	0.00
Pressure Pot	1,065	102,240	121°, 15 PSIG	0	0.00
Solder DUNK	135	405	260°C, 10SEC	0	0.00
Solderability	600	4,800	883 M2003	0	0.00
Temp Cycle	1,415	392,500	−65°C−150°C	0	0.00
Thermal Shock	50	5,000	−60°C−150°C	0	0.00